



US 20240224422A1

(19) **United States**

(12) **Patent Application Publication**
HIGASHI et al.

(10) **Pub. No.: US 2024/0224422 A1**

(43) **Pub. Date: Jul. 4, 2024**

(54) **WIRING BOARD**

(30) **Foreign Application Priority Data**

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Jan. 28, 2021 (JP) 2021-012421

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Publication Classification

(51) **Int. Cl.**
H05K 1/09 (2006.01)
B22F 7/04 (2006.01)

(52) **U.S. Cl.**
CPC **H05K 1/09** (2013.01); **B22F 7/04** (2013.01); **B22F 2301/10** (2013.01)

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(21) Appl. No.: **18/271,871**

(22) PCT Filed: **Jan. 24, 2022**

(86) PCT No.: **PCT/JP2022/002423**

§ 371 (c)(1),

(2) Date: **Jul. 12, 2023**

(57) **ABSTRACT**

A wiring board includes an insulation layer and an electrical conductor layer that are layered. The insulation layer is a glass ceramic. The electrical conductor layer is a sintered body of a plurality of crystallites containing copper as a main component. The plurality of crystallites include polygonal crystallites having linear sides. The plurality of crystallites are in contact with each other via the linear sides as grain boundaries.

